

Surface Mount Switching Multi-Chip Diode Array

(Pb) Lead(Pb)-Free

Features:

- * For General Purpose Switching Applications
- * Fast Switching Speed
- * High Conductance
- * Easily Connected As Full Wave Bridge

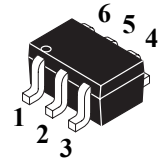
Mechanical Data:

- * Case : SOT-363
- * Case Material : Molded Plastic. UL Flammability Classification Rating 94V-0
- * Moisture Sensitivity : Level 1 per J-STD-020C
- * Terminals : Solderable per MIL-STD-202, Method 208
- * Polarity : See Diagram
- * Weight : 0.006 grams(appro)

MULTI-CHIP DIODES

150m AMPERES

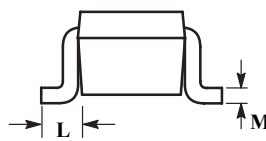
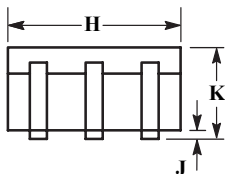
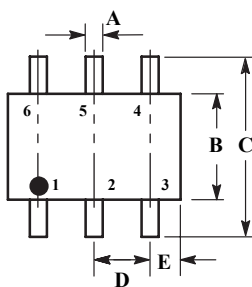
75 VOLTS



SOT-363

SOT-363 Outline Dimensions

Unit:mm



SOT-363

Dim	Min	Max
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 REF	
E	0.30	0.40
H	1.80	2.20
J	-	0.10
K	0.80	1.10
L	0.25	0.40
M	0.10	0.25

Maximum Ratings (T_A=25°C Unless otherwise noted)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RM} V _R	75	V
RMS Reverse Voltage	V _{R(RSM)}	53	V
Average Rectified Output Current ^(1,3)	I _O	150	mA
Non-Repetitive Forward Current @t=1.0μs @t=1.0s	I _{FSM}	2.0 1.0	A
Power Dissipation ^(1,3)	P _D	200	mW
Thermal Resistance, Junction to Ambient Air ^(1,3)	R _{θJA}	625	°C/W
Junction & Storage Temperature Range	T _j ,T _{stg}	-65 to +150	°C

Electrical Characteristics (T_A=25°C Unless otherwise noted)

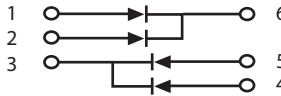
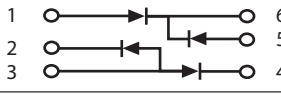
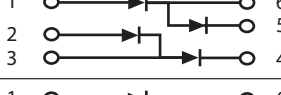
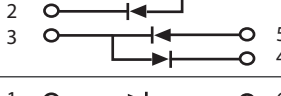
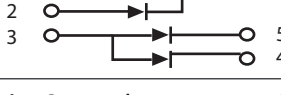
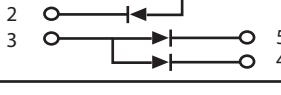
Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Breakdown Voltage ⁽²⁾ I _R =2.5μA	V _{(BR)R}	75	-	-	A
Reverse Current ⁽²⁾ V _R =75V V _R =20V	I _R	-	-	2.5 25	μA nA
Forward Voltage ⁽²⁾ I _F =1mA I _F =10mA I _F =50mA I _F =150mA	V _F	-	-	715 855 1000 1250	mA
Total Capacitance (V _R =0V, f=1.0MHz)	C _D	-	-	2.0	pF
Reverse Recover Time I _F = I _R = 10mA, I _{rr} = 0.1 x I _R , R _L = 100Ω	T _{rr}	-	-	4.0	nS

Notes: 1. Device mounted on FR-4 PC board with recommended pad layout.

2. Short duration test pulse used to minimize self-heating effect.

3. One or more diodes loaded.

Device Marking

Item	Marking	Equivalent Circuit diagram
BAV70DW	KJA	
BAV756DW	KCA	
BAV99BRW	KGJ	
BAV99DW	KJG	
BAW567DW	KAC	
BAW56DW	KJC	

Typical Characteristics

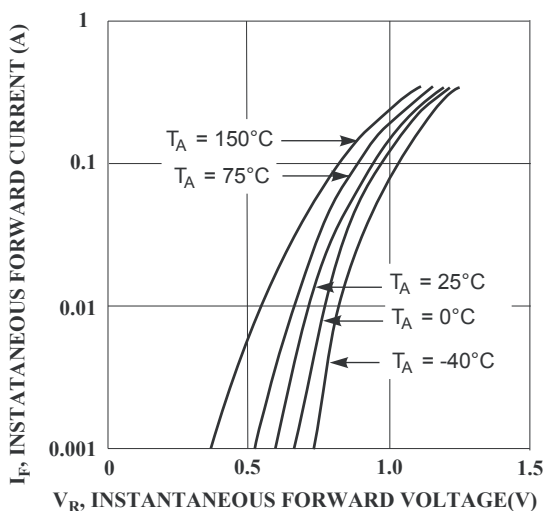


Fig.1 Forward Characteristics

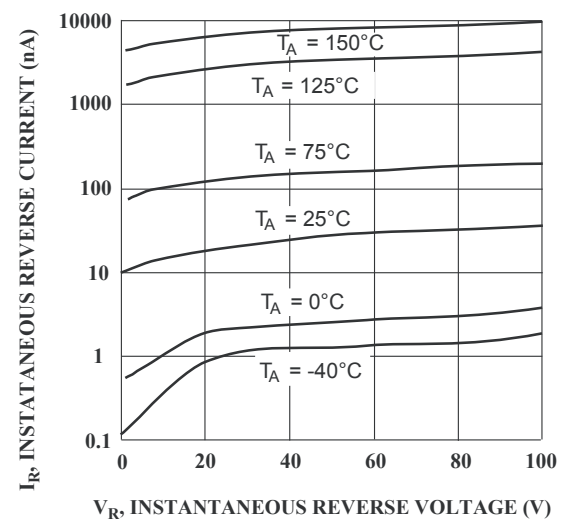


Fig.2 Typical Reverse Characteristics

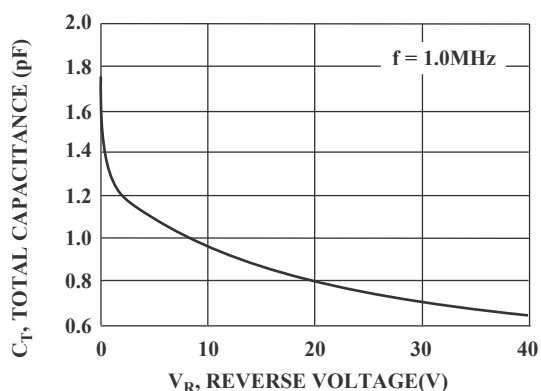


Fig.3 Typical Capacitance vs. Reverse Voltage

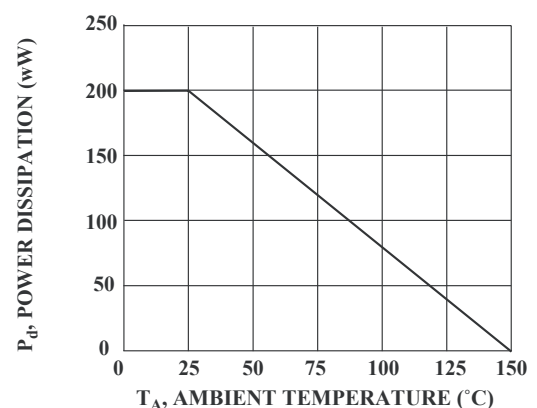


Fig.4 Power Derating Curve